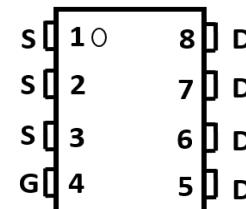
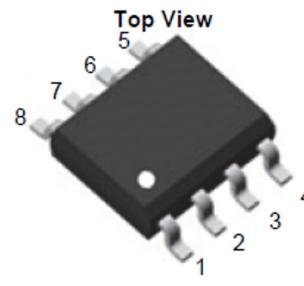


N-Channel Enhancement Mode Field Effect Transistor

RCP0112

Product Summary

- V_{DS} 100V
- I_D 12A
- $R_{DS(ON)}$ (at $V_{GS}=10V$) <17 mohm



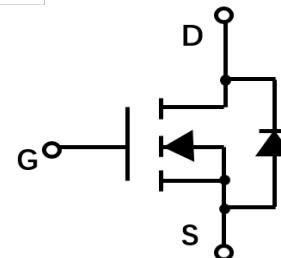
General Description

- Split Gate Trench MOSFET technology
- Excellent package for heat dissipation
- High density cell design for low $R_{DS(ON)}$

Applications

- DC/DC Primary Side Switch
- Telecom/Server
- Synchronous Rectification

SOP-8



■ Absolute Maximum Ratings ($T_A=25^\circ C$ unless otherwise noted)

Parameter	Symbol	Maximum	Unit
Drain-source Voltage	V_{DS}	100	V
Gate-source Voltage	V_{GS}	± 20	V
Drain Current $T_A=25^\circ C$	I_D	12	A
$T_A=100^\circ C$	I_D	7.5	
Pulsed Drain Current ^A	I_{DM}	70	A
Avalanche Energy, Single Pulse($L=0.5mH$)	E_{AS}	80	mJ
Total Power Dissipation ^B	P_D	3.1	W
Junction and Storage Temperature Range	T_J, T_{STG}	-55~+150	°C

■ Thermal resistance

Parameter	Symbol	Typ	Max	Units
Thermal Resistance Junction-to-Ambient ^C	$R_{\theta JA}$	31	40	°C/W
Thermal Resistance Junction-to-Ambient ^C		59	75	
Thermal Resistance Junction-to-Lead		16	24	

■ Ordering Information (Example)

PREFERRED P/N	PACKING CODE	Marking	MINIMUM PACKAGE(pcs)	INNER BOX QUANTITY(pcs)	OUTER CARTON QUANTITY(pcs)	DELIVERY MODE
RCP0112	F2		3000	9000	90000	13" reel

N-Channel Enhancement Mode Field Effect Transistor

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■ Electrical Characteristics ($T_J=25^\circ\text{C}$ unless otherwise noted)

Parameter	Symbol	Conditions	Min	Typ	Max	Units
Static Parameter						
Drain-Source Breakdown Voltage	BV_{DSS}	$V_{\text{GS}}=0\text{V}, I_{\text{D}}=250\mu\text{A}$	100			V
Zero Gate Voltage Drain Current	I_{DSS}	$V_{\text{DS}}=100\text{V}, V_{\text{GS}}=0\text{V}, T_J=25^\circ\text{C}$			1	μA
Gate-Body Leakage Current	I_{GSS}	$V_{\text{GS}}= \pm 20\text{V}, V_{\text{DS}}=0\text{V}$			± 100	nA
Gate Threshold Voltage	$V_{\text{GS}(\text{th})}$	$V_{\text{DS}}=V_{\text{GS}}, I_{\text{D}}=250\mu\text{A}$	1.0	1.7	3.0	V
Static Drain-Source On-Resistance	$R_{\text{DS}(\text{ON})}$	$V_{\text{GS}}=10\text{V}, I_{\text{D}}=10\text{A}$		14.5	17	$\text{m}\Omega$
Diode Forward Voltage	V_{SD}	$I_{\text{S}}=12\text{A}, V_{\text{GS}}=0\text{V}$			1.3	V
Maximum Body-Diode Continuous Current	I_{S}				12	A
Gate resistance	R_{G}	f=1MHz, Open drain		1		Ω
Dynamic Parameters						
Input Capacitance	C_{iss}	$V_{\text{DS}}=50\text{V}, V_{\text{GS}}=0\text{V}, f=1\text{MHz}$		1135		pF
Output Capacitance	C_{oss}			399		
Reverse Transfer Capacitance	C_{rss}			18		
Switching Parameters						
Total Gate Charge	Q_{g}	$V_{\text{GS}}=10\text{V}, V_{\text{DS}}=50\text{V}, I_{\text{D}}=10\text{A}$		16		nC
Gate-Source Charge	Q_{gs}			5.6		
Gate-Drain Charge	Q_{gd}			2.4		
Reverse Recovery Chrage	Q_{rr}	$I_{\text{F}}=10\text{A}, \text{di}/\text{dt}=100\text{A}/\text{us}$		42		ns
Reverse Recovery Time	t_{rr}			39.8		
Turn-on Delay Time	$t_{\text{D}(\text{on})}$	$V_{\text{GS}}=10\text{V}, V_{\text{DD}}=50\text{V}, I_{\text{D}}=10\text{A}$ $R_{\text{GEN}}=2.2\Omega$		39.2		ns
Turn-on Rise Time	t_{r}			11		
Turn-off Delay Time	$t_{\text{D}(\text{off})}$			53.2		
Turn-off fall Time	t_{f}			15.8		

A. Repetitive rating; pulse width limited by max. junction temperature.

B. P_d is based on max. junction temperature, using $\leq 10\text{s}$ junction-ambient thermal resistance.

C. The value of R_{GJA} is measured with the device mounted on 1in^2 FR-4 board with 2oz. Copper, in a still air environment with $T_A=25^\circ\text{C}$. The value in any given application depends on the user's specific board design.

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■ Typical Performance Characteristics

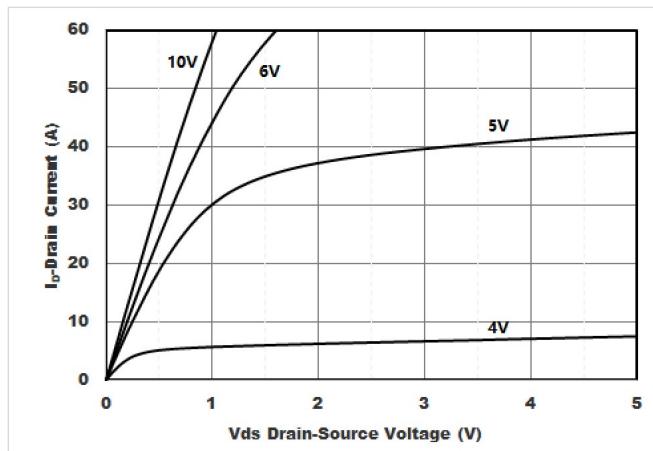


Figure1. Output Characteristics

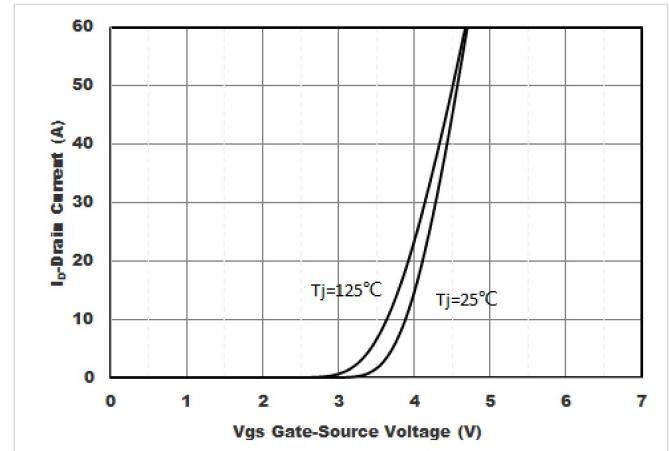


Figure2. Transfer Characteristics

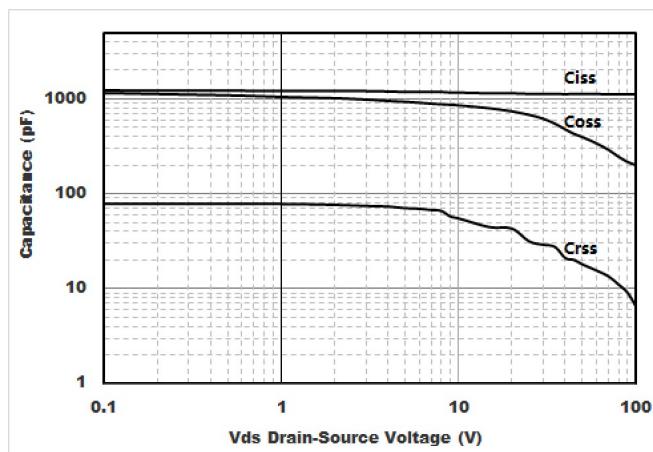


Figure3. Capacitance Characteristics

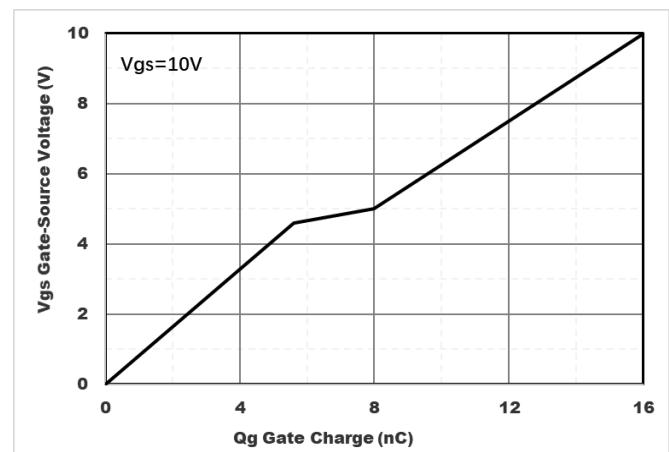


Figure4. Gate Charge

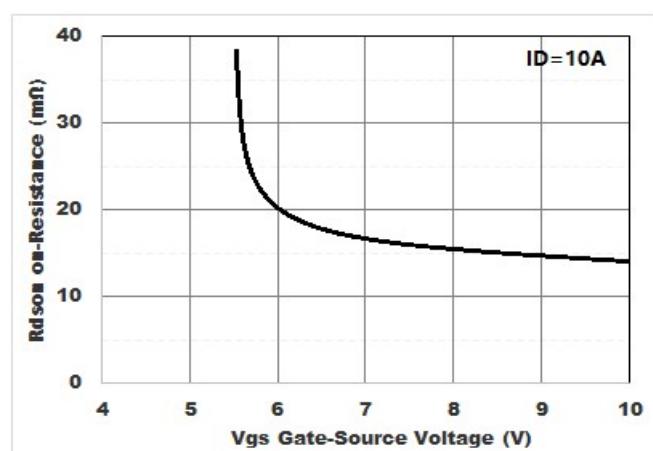


Figure5. Drain-Source on Resistance

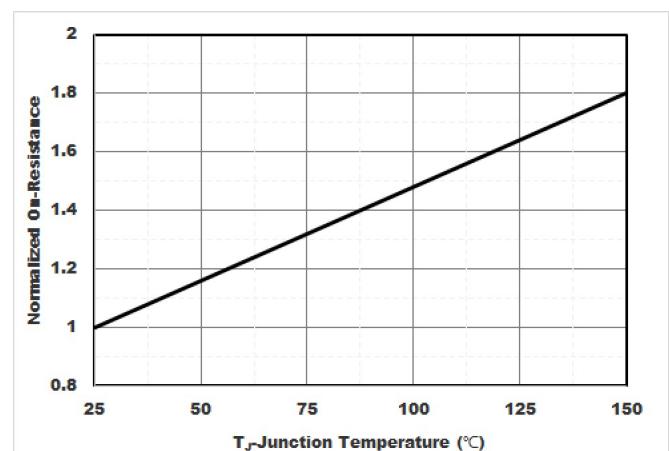


Figure6. Drain Current

N-Channel Enhancement Mode Field Effect Transistor

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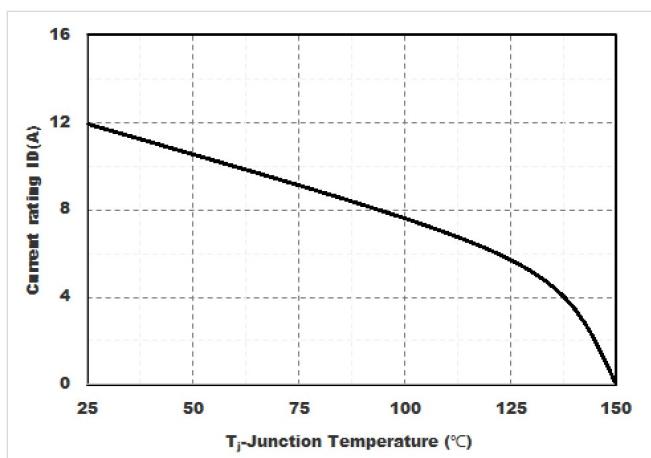


Figure7. Drain current

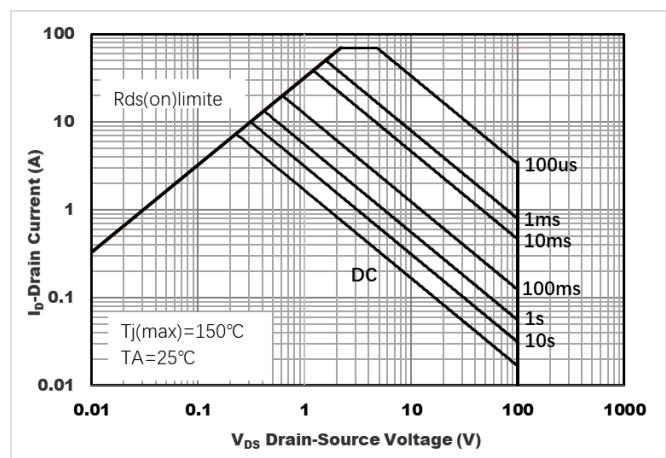


Figure8. Safe Operation Area

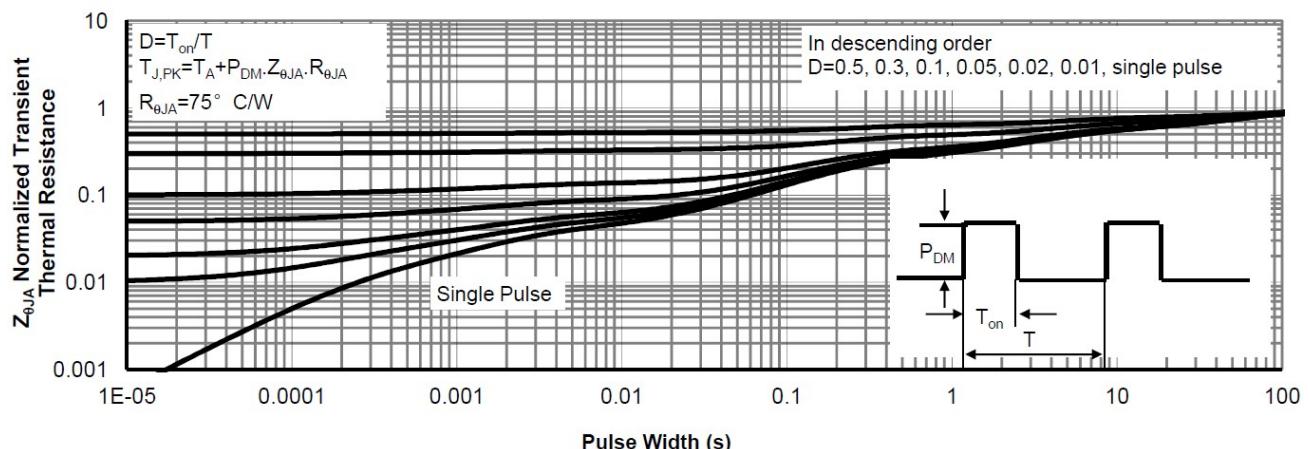
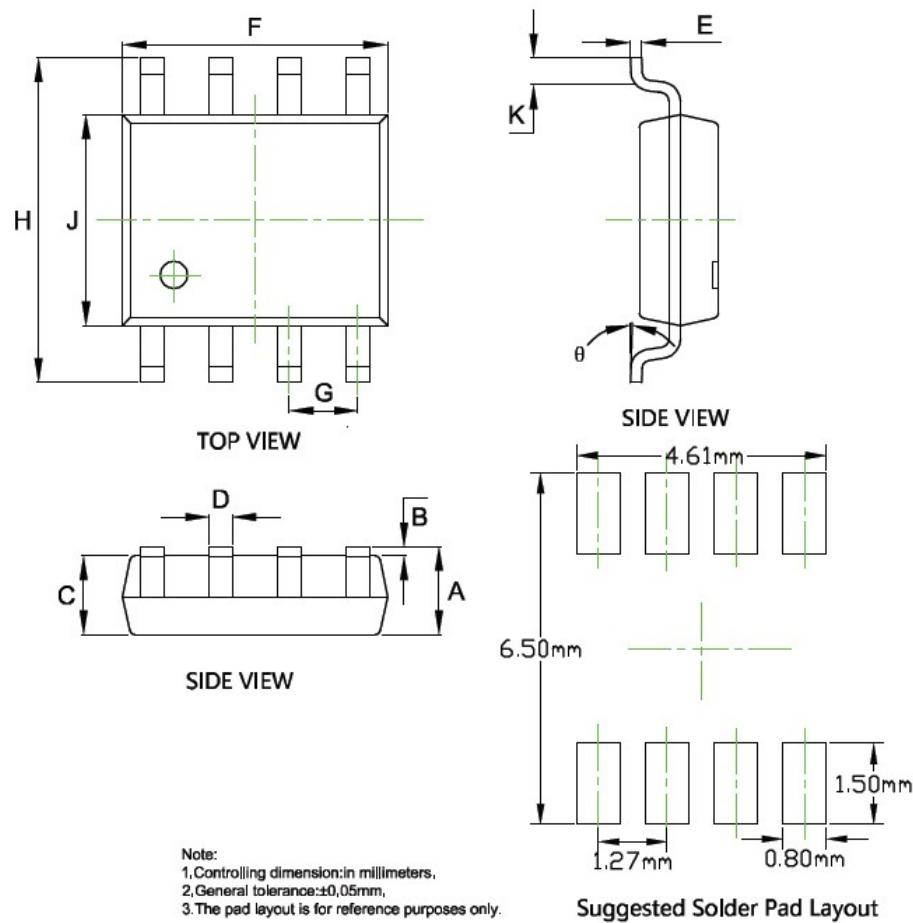


Figure9. Normalized Maximum Transient Thermal Impedance

N-Channel Enhancement Mode Field Effect Transistor

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■ SOP-8 Package information



SYMBOL	INCHES		Millimeter	
	MIN.	MAX.	MIN.	MAX.
A	0.053	0.069	1.350	1.750
B	0.004	0.010	0.100	0.250
C	0.053	0.061	1.350	1.550
D	0.013	0.020	0.330	0.510
E	0.007	0.010	0.170	0.250
F	0.189	0.197	4.800	5.000
G	0.050BSC		1.270BSC	
H	0.228	0.244	5.800	6.200
J	0.150	0.157	3.800	4.000
K	0.016	0.050	0.400	1.270
θ	0°	8°	0°	8°